EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2505491	selective adj (metallizing or metalized) with layer or resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:22
S2	2505486	selective adj (metallizing or metalized with seeding) with layer or resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:23
S3	2505485	selective adj (metallizing with seeding) with layer or resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:23
S4	0	selective adj (metallizing with seeding) with resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:23
S5	0	selective adj (metallizing with seeding) with layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:24
S6	0	selective adj (metallizing with seeding)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:24
S7	77	(metallizing or metalized) with seeding	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:26
S8	13	(metallizing or metalized) with seeding same solvent	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:46

S9	2	(metallizing or metalized) with seeding same solvent and 428/457.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 12:47
S10	0	selective adj (metallizing with seeding) and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 13:56
S11	12	(metallizing with seeding) and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 13:56
S12	2	(metallizing with seeding) and ceramic and plastic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2008/10/17 14:03
S13	297619	selective and metallized not seeding or seed	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	OFF	2008/10/20 09:50
S14	37747	selective adj metallized not seeding or seed and deposition	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	OFF	2008/10/20 09:51
S15	8	selective adj metallized not (seeding or seed) and deposition	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	OFF	2008/10/20 09:51
S16	180949	selective adj (metallizing with seeding) with layer or resin and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/04/09 17:25
S17	56535	selective adj (metallizing with seeding) with layer or resin and ceramic	US-PGPUB	AND	ON	2009/04/09 17:25

S18	0	selective adj (metallizing adj seeding) with layer and ceramic	US-PGPUB	AND	ON	2009/04/09 17:26
S19	0	selective adj (metallizing adj2 seeding) with layer and ceramic	US-PGPUB	AND	ON	2009/04/09 17:26
S20	0	selective adj (metallizing adj5 seeding) with layer and ceramic	US-PGPUB	AND	ON	2009/04/09 17:26
S21	0	selective adj (metallizing adj5 seed $3) with layer and ceramic	US-PGPUB	AND	ON	2009/04/09 17:26
S22	0	selective adj (metallizing adj5 seed $3)	US-PGPUB	AND	ON	2009/04/09 17:27
S23	683	selective adj (metal$7)	US-PGPUB	AND	ON	2009/04/09 17:27
S24	111	selective adj (metal$7) and (seed$3 with layer)	US-PGPUB	AND	ON	2009/04/09 17:27
S25	24	selective adj (metal$7) and (seed$3 with layer) and ceramic	US-PGPUB	AND	ON	2009/04/09 17:28
S26	117	(selective adj3 seed$3) with layer	US-PGPUB	AND	ON	2009/04/09 17:31
S27	4	(selective adj3 metal$3 adj3 seed$3) with layer	US-PGPUB	AND	ON	2009/04/09 17:32
S28	180960	selective adj (metallizing or metalized) with layer or resin and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/04/09 17:35
S29	18	selective adj (metallizing or metalized) and ceramic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/04/09 17:35
S30	1	"4981715".pn.	USPAT	OR	OFF	2009/04/09 17:38
S31	1	"4757035".pn.	USPAT	OR	OFF	2009/04/09 17:39
S32	1	"4618568".pn.	USPAT	OR	OFF	2009/04/09 17:40
S33	29	electrodeposition adj2 ceramic	US-PGPUB; USPAT	OR	ON	2009/04/09 17:49

S34	3	electrodeposition adj2 ceramic and (seed$3 with layer)	US-PGPUB; USPAT	OR	ON	2009/04/09 17:49
S35	0	selective with electrodeposition with ceramic and (seed$3 with layer)	US-PGPUB; USPAT	OR	ON	2009/04/09 17:51
S36	258	electrodeposition with ceramic	US-PGPUB; USPAT	OR	ON	2009/04/09 17:51
S37	86	electrodeposition with ceramic and selective	US-PGPUB; USPAT	OR	ON	2009/04/09 17:51
S38	0	electrodeposition with ceramic and selective and seeding	US-PGPUB; USPAT	OR	ON	2009/04/09 17:52
S39	48	electrodeposition with ceramic and selective and seed$3	US-PGPUB; USPAT	OR	ON	2009/04/09 17:52
S40	7219	electroless with metal with deposition	US-PGPUB; USPAT	OR	ON	2009/04/09 17:54
S41	458	selective with (electroless with metal with deposition)	US-PGPUB; USPAT	AND	ON	2009/04/09 17:54
S42	198	selective with (electroless with metal with deposition) and seed$ with layer	US-PGPUB; USPAT	AND	ON	2009/04/09 17:54
S43	186	selective with (electroless with metal with deposition) and ceramic	US-PGPUB; USPAT	AND	ON	2009/04/09 17:57
S44	159	selective with (electroless with metal with deposition) and ceramic and solution	US-PGPUB; USPAT	AND	ON	2009/04/09 17:57
S45	28	selective with (electroless with metal with deposition) and ceramic and (seed$ with solution)	US-PGPUB; USPAT	AND	ON	2009/04/09 17:59
S46	549	electroless with metal with ceramic	US-PGPUB; USPAT	AND	ON	2009/04/09 18:01
S47	8	selective with electroless with metal with ceramic	US-PGPUB; USPAT	AND	ON	2009/04/09 18:02
S48	203	electroless with metal with ceramic	US-PGPUB	AND	ON	2009/04/09 18:04

4/10/2009 9:50:59 AM
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